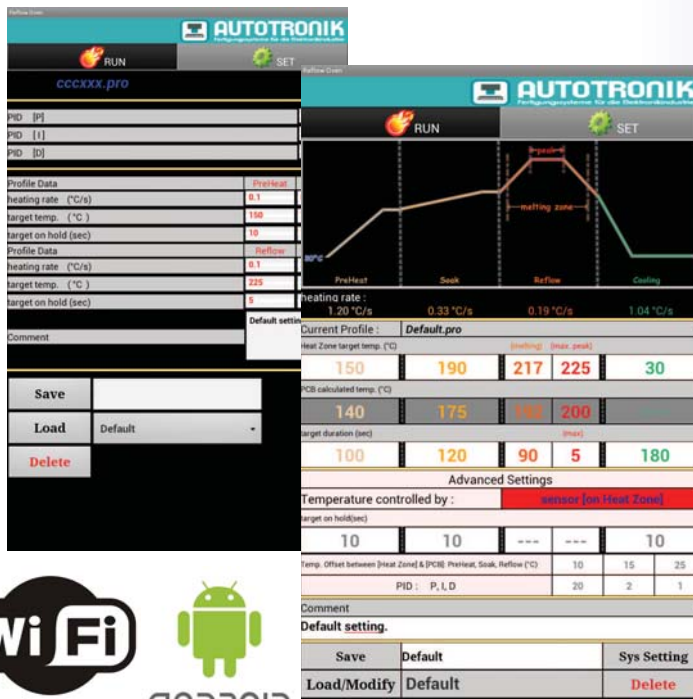


# Bench-top / Batch Reflow Oven

## BT301

Dynamic Thermal Profile using a Batch Reflow Oven with Android™ Operating System

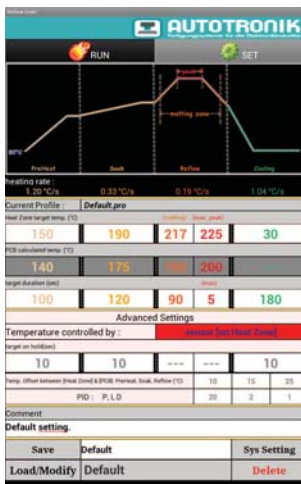
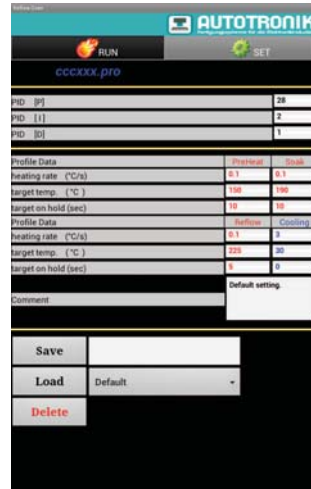
Match your thermal process specifications for preheat, soak, reflow, and cooling on the first PCB you produce with by using revolutionary new BT301 Batch Reflow Oven. Having the thermal conditions of an inline reflow system in a bench-top unit with a full dynamic thermal process.



The BT301 is ideal for product development, prototyping, and small series production. Solder profiles are easily set-up and stored through the control app of the BT301's exclusive hardware control and Android operating system. The dynamic control system takes care of size and complexity of your assembly and makes it a closed loop process, something only large and costly thermal systems can normally offer.

## Features

- ⊙ Real time close loop PID temperature control for leadfree profile
- ⊙ Quick Smart programming by rising rate control (degree change per second)
- ⊙ Infrared and forced convection combine for efficient lead-free reflow
- ⊙ Real time temperature profile display
- ⊙ Android system on multi-core CPU platform
- ⊙ 7" touch screen high resolution LCD display
- ⊙ Compact design ideal for labs, schools, prototyping and low-volume job shops
- ⊙ WiFi temperature profile printing and data storage

The screenshot shows the AUTOTRONIK control interface with profile data and settings. The profile data includes heating rate (0.1 °C/s), target temp (150 °C), target on hold (10 sec), heating rate (0.1 °C/s), target temp (225 °C), and target on hold (5 sec). The settings include PID parameters (P, I, D) and a comment field.

Profile Data	Preheat	Soak
heating rate (°C/s)	0.1	0.1
target temp. (°C)	150	150
target on hold (sec)	10	10
Profile Data	Reflow	Cooling
heating rate (°C/s)	0.1	0
target temp. (°C)	225	20
target on hold (sec)	5	0



## Real-Time dynamic thermal Control via On-Board measuring device

The BT301 has an advanced setting in which you can turn on the real time dynamic process. The unit can then via real-time feedback from the measuring system which is attached at a strategic location on the PCB surface.

The heater control and fan speed is based on the actual temperature measured on the product. The target temperature is equal to the dynamic measuring system temperature and there is no offset, making this a perfect tool for prototyping and small series.

## Specification

### Machine Model

- Applicable solder types
- PCB holding size
- PCB effective heating area
- Heating method
- Temperature range
- Temperature control method
- Warm-up time
- Computer control
- Display panel
- Temperature control setting
- Temperature profile display
- Temp profile printing
- Storage
- Electrical
- Power
- Dimensions
- Weight

### BT301

- Lead-Free and Leaded
- 350 mm x 240 mm
- 250 mm x 200 mm
- Quartz IR & Forced Hot Air Convection
- Ambient - 310 °C
- Real time close loop PID temperature control for lead free profile approx. 2 min.
- Build-in dual core CPU on board computer
- 7" touch screen high resolution LCD display
- Quick smart profile programming by temperature rising rate control (degree change per second)
- Real time temperature profile display
- WiFi temperature profile printing
- External data storage via WiFi connection
- 230 V, Single Phase, 50/60 Hz, 30A
- 3000W
- 690 mm L x 470 mm W x 270 mm H
- approx. 45 Kg

\* We reserve the right to make changes without notice.